

Fast Rectifiers

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter	Value				Units
		3A	3B	3C	3D	Onits
V _{RRM}	Maximum Repetitive Reverse Voltage	50	100	150	200	V
I _{F(AV)}	Average Rectified Forward Current, .375 " lead length @ T _A = 75°C	3.0			A	
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	100			A	
T _{stg}	Storage Temperature Range	-55 to +150			°C	
TJ	Operating Junction Temperature	-55 to +150			°C	

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

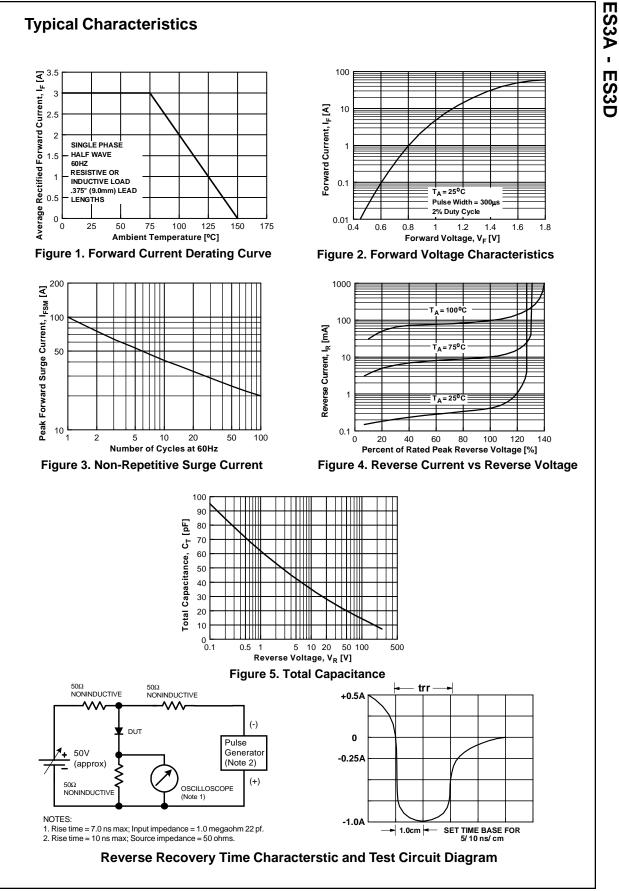
Symbol	Parameter	Value	Units	
P _D	Power Dissipation	1.66	W	
R _{0JA}	Thermal Resistance, Junction to Ambient*	47	°C/W	
$R_{ extsf{ hetaJL}}$	Thermal Resistance, Junction to Lead*	12	°C/W	

*Device mounted on FR-4 PCB 0.013 mm.

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Device				Units
				3B	3C	3D
V _F	Forward Voltage @ 3.0 A		0.90			V
t _{rr}	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$		20			ns
I _R	Reverse Current @ rated V_R	T _A = 25°C T _A = 100°C	10 500			μΑ μΑ
C _T	Total Capacitance $V_R = 4.0 V, f = 1.0 MHz$		45			pF

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ES3A-ES3D, Rev. C

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